

DECLARATION FOR PATENT APPLICATION

As a below named inventor, I hereby declare: that my residence, post office address and citizenship are as stated below next to my name; that I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

ISOTROPIC POWDERY MAGNET MATERIAL, PROCESS FOR PREPARING AND RESIN-BONDED
MAGNET

the specification of which (check only one item)

☒ is attached hereto.

☐ was filed on _____ as
United States application Serial No. _____
and was amended on _____ (if applicable).

☐ was filed on _____ as
PCT international application No. _____
and was amended under PCT Article 19 on _____ (if applicable).

I hereby state that I have reviewed and understand the contents of the above-identified application, including the claim(s), as amended by an amendment referred to above, I acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, § 1.56(a).

I hereby claim foreign priority benefits under Title 35, United States Code, § 119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Prior Foreign Application(s):

Priority Claimed

<u>2000-158807</u> (Number)	<u>Japan</u> (Country)	<u>5/29/2000</u> (Month/Day/Year Filed)	<input checked="" type="checkbox"/> Yes <input type="checkbox"/> No
<u>2000-160514</u> (Number)	<u>Japan</u> (Country)	<u>5/30/2000</u> (Month/Day/Year Filed)	<input checked="" type="checkbox"/> Yes <input type="checkbox"/> No
<u>2000-162713</u> (Number)	<u>Japan</u> (Country)	<u>5/31/2000</u> (Month/Day/Year Filed)	<input checked="" type="checkbox"/> Yes <input type="checkbox"/> No
<u>2001-151392</u> (Number)	<u>Japan</u> (Country)	<u>5/21/2001</u> (Month/Day/Year Filed)	<input type="checkbox"/> Yes <input checked="" type="checkbox"/> No
_____ (Number)	_____ (Country)	_____ (Month/Day/Year Filed)	<input type="checkbox"/> Yes <input type="checkbox"/> No

I hereby claim the benefit under Title 35, United States Code § 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Regulations, § 1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

_____ (Application Serial No.)	_____ (Filing Date)	_____ (Status)(patented, pending, abandoned)
_____ (Application Serial No.)	_____ (Filing Date)	_____ (Status)(patented, pending, abandoned)

I hereby claim the benefit under Title 35, United States Code, § 119(e) of any United States provisional application(s) listed below:

_____ (Application Serial No.)	_____ (Filing Date)
_____ (Application Serial No.)	_____ (Filing Date)

I hereby appoint as principal attorneys R. Eugene Varnnell, Jr., Reg. No. 29,728, and Debra Shoemaker, Reg. No. 47,941. Please direct all communications to the following address:

VARNDELL & VARNDELL, PLLC
106-A SOUTH COLUMBUS STREET
ALEXANDRIA, VA 22314
(703) 683-9730

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

GIVEN NAME(S) Takahiko	FAMILY NAME IRIYAMA	INVENTOR'S SIGNATURE <i>Takahiko Iriyama</i>	DATE May 22, 2001
RESIDENCE (City, State & Country) c/o 30, Daidocho 2-chome, Minami-ku, Nagoya-shi, Aichi-ken, Japan, Daido Steel Co., Ltd., Research &			CITIZENSHIP Japan
POST OFFICE ADDRESS (Complete Street Address including City, State & Country) Development Lab. the same as above			
GIVEN NAME(S) Ryo	FAMILY NAME OMATSUZAWA	INVENTOR'S SIGNATURE <i>Ryo Omatsuzawa</i>	DATE May 22, 2001
RESIDENCE (City, State & Country) c/o 30, Daidocho 2-chome, Minami-ku, Nagoya-shi, Aichi-ken, Japan, Daido Steel Co., Ltd., Research &			CITIZENSHIP Japan
POST OFFICE ADDRESS (Complete Street Address including City, State & Country) Development Lab. the same as above			
GIVEN NAME(S) Takayuki	FAMILY NAME NISHIO	INVENTOR'S SIGNATURE <i>Takayuki Nishio</i>	DATE May 22, 2001
RESIDENCE (City, State & Country) c/o 30, Daidocho 2-chome, Minami-ku, Nagoya-shi, Aichi-ken, Japan, Daido Steel Co., Ltd., Research &			CITIZENSHIP Japan
POST OFFICE ADDRESS (Complete Street Address including City, State & Country) Development Lab. the same as above			
GIVEN NAME(S)	FAMILY NAME	INVENTOR'S SIGNATURE	DATE
RESIDENCE (City, State & Country)			CITIZENSHIP
POST OFFICE ADDRESS (Complete Street Address including City, State & Country)			
GIVEN NAME(S)	FAMILY NAME	INVENTOR'S SIGNATURE	DATE
RESIDENCE (City, State & Country)			CITIZENSHIP
POST OFFICE ADDRESS (Complete Street Address including City, State & Country)			
GIVEN NAME(S)	FAMILY NAME	INVENTOR'S SIGNATURE	DATE
RESIDENCE (City, State & Country)			CITIZENSHIP
POST OFFICE ADDRESS (Complete Street Address including City, State & Country)			

☐ Similar information and signature for sixth and subsequent joint inventors on attached sheet.